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Structure	Silicon Monolithic Integrated Circuit
Product	Power Management for Cellular Phone

Type BH6038KN

Function• A built-in 7-channel CMOS-typed series regulator.
• A built-in Lithium battery charge control circuit.

⊖Absolute Maximum Ratings (Ta = 25°C)

	- /				
Parameter	Symbol	Range		Unit	Condition
Maximum Supply Voltage	V _{MAX}	7.0		V	
Power Dissipatin 1	Pd1	500	(*1)	mW	
Power Dissipatin 2	P _{d2}	700	(*2)	mW	
Operating Temperature Range	Topr	-30 ~ +75		°C	
Storage Temperature Range	T _{sta}	-55 ~ +125		ູ	

(*1) This value is the allowable loss of a single package. Reduce 5.0mW/°C when Ta=25°C or above.

(*2) Reduce 7.0mW/°C when Ta=25°C or above.

When mounted on a 70 mm \times 70 mm \times 1.6 mm thick glass epoxy PCB.

○Recommend Movement Range (Ta = -30~+80°C)

Parameter	Symbol	Range	Unit	Condition
Battery Voltage	VBAT	3.20~4.50	V	
Adapter Voltage	VADP	4.60~5.90	V	
Operating Temperature range	Topr	-30~+75	℃	

This product is not especially designed to be protected from radioactivity.

Status of this document

The Japanese version of this document is the formal specification. A customer may use this translation version only for a reference to help reading the formal version. If there are any differences in translation version of this document, formal version takes priority.

Use-related Cautions

The product described in this specification is designed to be used with ordinary electronic equipment or devices (such as audio-visual equipment, office-automation equipment, communications devices, electrical appliances, and electronic toy).

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OElectrical Characteristics

Unless otherwise specified, Ta=+25°C, VBAT=3.6V

	vise specified, Ta=+2 Parameter	Symbol	MIN	Spec TYP	MAX	Unit	Condition
REG1 Output Voltage		V01	2.79	2.85	2.91	v	lo=50mA
REG1 Load Stability		ΔVL1	-	10	65	mV	lo=1~75mA
	REG1I Input Voltage Stability		-	10	60	mV	VBAT=3.3~4.5V, lo=50mA
	REG2 Output Voltage		1.79	1.85	1.91	V	lo=30mA
REG2 Load		VO2 VO2	-	10	65	mV	lo=1~45mA
REG2 Input	t Voltage Stability	∆Vl2	-	10	60	mV	VBAT=3.3~4.5V、lo=30mA
REG3 Outp		VO3	2.79	2.85	2.91	V	lo=120mA
REG3d Sta	bility	∆VL3	-	15	80	mV	lo=1~180mA
REG3 Input	t Voltage Stability	∆Vl3	-	10	60	mV	VBAT=3.3~4.5V、lo=120mA
REG4 Outp		VO4	1.79	1.85	1.91	V	lo=50mA
REG4d Sta		∆VL4	-	10	65	mV	lo=1~75mA
REG4 Input	t Voltage Stability	∆Vl4	-	10	60	mV	VBAT=3.3~4.5V, lo=50mA
REG5 Outp		VO5	2.79	2.85	2.91	v	lo=80mA
REG5d Sta		∆VL5	-	15	80	mV	lo=1~120mA
	t Voltage Stability	∆VI5	-	10	60	mV	VBAT=3.3~4.5V, lo=80mA
REG6 Outp		VO6	2.79	2.85	2.91	v	lo=40mA
REG6d Sta		∆VL6	-	15	80	mV	lo=1~60mA
REG6 Inpu	t Voltage Stability	∆Vl6	-	10	60	mV	VBAT=3.3~4.5V, lo=40mA
RFREG Output Voltage		VORF	2.74	2.8	2.86	v	lo=60mA
Fred Stability		∆VLRF	-	20	60	mV	lo=1~60mA
	ntroller (With 0.33Ω		ent Detection		Connected		
Charge Co	ntrol Voltage	VCHG	4.17	4.20	4.23	v	Ta=-10~60℃ Charge current : 60mA
Bapidity Ch	arge Current	ICHG	0.9C	1C	1.1C	mA	1C=500mA
SETR Curr		ISETR	80	90	100	mA	
Overload Protection							
detect current		ILIM	1.8C	2.0C	2.2C	mA	
Convergence detect current		IDET08C	0.7C	0.8C	0.9C	mA	
Forced cha		ICMCG	17	43	69	mA	VBAT=1.89V
	rge start voltage	VCMCG	1.9	2.0	2.1	V	
	6.0V detect voltage	VAD60	5.9	6.1	6.3	v	In voltage rise
Adapter	Hysteresis voltage	∆VAD60	20	50	100	mV	
Detection	3.0V detect voltage	VAD30	2.8	3.0	3.2	v	In voltage fall
	Hysteresis voltage	∆VAD30	20	50	100	mV	
	5.0V						
	detect voltage	VVD50	4.85	5.1	5.35	V	In voltage fall
Battery	Hysteresis voltage	∆VVD50	50	100	150	mV	
Voltage	4.43V detect voltage	VVD43	4.43	4.56	4.69	v	In voltage fall
	Hysteresis voltage	∆VVD43	20	50	100	mV	
	3.3V detect voltage	VVD33	3.25	3.42	3.59	v	In voltage fall

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OPackage Diagram



UQFN48 (

(unit:mm)



OBlock Diagram



OTerminal table

PIN	BALL Name	PIN	BALL Name
1	TEST	25	RSTC
2	GND_B	26	SW3
3	RFREGCNT	27	DET34t
4	RF_REG	28	DET34OUT
5	REG34ON	29	REG4
6	CPUDO	30	REG3
7	MONION	31	VBAT1
8	VBAT4	32	REG1
9	VIB	33	BACKUP
10	SW3CNT	34	DET12t
11	TOUT	35	DET12OUT
12	LED	36	REG2
13	GND_LE	37	REG_REF_M
14	TMPMONI	38	GND_M
15	CURMONI	39	REG_REF_B
16	POWEROK	40	CPUCS
17	VADP	41	CPUDI
18	PGATE	42	CPUCLK
19	CURH	43	BATMONI
20	BAT2	44	REG5
21	BAT1	45	VBAT2
22	REF	46	REG6
23	TEMP	47	VBAT3
24	GND_C	48	VIBCNT



OUse-related Cautions

(1) Absolute maximum ratings

If applied voltage (VDD, VIN), operating temperature range (Topr), or other absolute maximum ratings are exceeded, there is a risk of damage. Since it is not possible to identify short, open, or other damage modes, if special modes in which absolute maximum ratings are exceeded are assumed, consider applying fuses or other physical safety measures.

(2) Recommended operating range

This is the range within which it is possible to obtain roughly the expected characteristics. For electrical characteristics, it is those that are guaranteed under the conditions for each parameter. Even when these are within the recommended operating range, voltage and temperature characteristics are indicated.

(3) Reverse connection of power supply connector

There is a risk of damaging the LSI by reverse connection of the power supply connector. For protection from reverse connection, take measures such as externally placing a diode between the power supply and the power supply pin of the LSI.

(4) Power supply lines

In the design of the board pattern, make power supply and GND line wiring low impedance.

When doing so, although the digital power supply and analog power supply are the same potential, separate the digital power supply pattern and analog power supply pattern to deter digital noise from entering the analog power supply due to the common impedance of the wiring patterns. Similarly take pattern design into account for GND lines as well.

Furthermore, for all power supply pins of the LSI, in conjunction with inserting capacitors between power supply and GND pins, when using electrolytic capacitors, determine constants upon adequately confirming that capacitance loss occurring at low temperatures is not a problem for various characteristics of the capacitors used.

(4) GND voltage

Make the potential of a GND pin such that it will be the lowest potential even if operating below that. In addition, confirm that there are no pins for which the potential becomes less than a GND by actually including transition phenomena.

(6) Shorts between pins and misinstallation

When installing in the set board, pay adequate attention to orientation and placement discrepancies of the LSI. If it is installed erroneously, there is a risk of LSI damage. There also is a risk of damage if it is shorted by a foreign substance getting between pins or between a pin and a power supply or GND.

(7) Operation in strong magnetic fields

Be careful when using the LSI in a strong magnetic field, since it may malfunction.

(8) Inspection in set board

When inspecting the LSI in the set board, since there is a risk of stress to the LSI when capacitors are connected to low impedance LSI pins, be sure to discharge for each process. Moreover, when getting it on and off of a jig in the inspection process, always connect it after turning off the power supply, perform the inspection, and remove it after turning off the power supply. Furthermore, as countermeasures against static electricity, use grounding in the assembly process and take appropriate care in transport and storage.

(9) Input pins

Parasitic elements inevitably are formed on an LSI structure due to potential relationships. Because parasitic elements operate, they give rise to interference with circuit operation and may be the cause of malfunctions as well as damage. Accordingly, take care not to apply a lower voltage than GND to an input pin or use the LSI in other ways such that parasitic elements operate. Moreover, do not apply a voltage to an input pin when the power supply voltage is not being applied to the LSI. Furthermore, when the power supply voltage is being applied, make each input pin a voltage less than the power supply voltage as well as within the guaranteed values of electrical characteristics.

(10) Ground wiring pattern

When there is a small signal GND and a large current GND, it is recommended that you separate the large current GND pattern and small signal GND pattern and provide single point grounding at the reference point of the set so that voltage variation due to resistance components of the pattern wiring and large currents do not cause the small signal GND voltage to change. Take care that the GND wiring pattern of externally attached components also does not change.

(11) Externally attached capacitors

When using ceramic capacitors for externally attached capacitors, determine constants upon taking into account a lowering of the rated capacitance due to DC bias and capacitance change due to factors such as temperature.

(12) Thermal shutdown circuit (TSD)

When junction temperatures become 150°C (typ) or higher, the thermal shutdown circuit operates and turns a switch OFF. The thermal shutdown circuit, which is aimed at isolating the LSI from thermal runaway as much as possible, is not aimed at the protection or guarantee of the LSI. Therefore, do not continuously use the LSI with this circuit operating or use the LSI assuming its operation.

(13) Thermal design

Perform thermal design in which there are adequate margins by taking into account the permissible dissipation (Pd) in actual states of use.

Notes

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Please contact our sales offices for details ;

U.S.A / San Diego Atlanta Dallas	TEL : +1(858)625-3630 TEL : +1(770)754-5972 TEL : +1(972)312-8818	FAX : +1(858)625-3670 FAX : +1(770)754-0691 FAX : +1(972)312-0330
Germany / Dusseldorf	TEL : +49(2154)9210	FAX : +49(2154)921400
United Kingdom / London	TEL:+44(1)908-282-666	FAX : +44(1)908-282-528
France / Paris	TEL : +33(0)1 56 97 30 60	FAX : +33(0) 1 56 97 30 80
China / Hong Kong Shanghai Dilian Beijing	TEL : +852(2)740-6262 TEL : +86(21)6279-2727 TEL : +86(411)8230-8549 TEL : +86(10)8525-2483	FAX : +852(2)375-8971 FAX : +86(21)6247-2066 FAX : +86(411)8230-8537 FAX : +86(10)8525-2489
Taiwan / Taipei	TEL : +866(2)2500-6956	FAX : +866(2)2503-2869
Korea / Seoul	TEL : +82(2)8182-700	FAX : +82(2)8182-715
Singapore	TEL : +65-6332-2322	FAX : +65-6332-5662
Malaysia / Kuala Lumpur	TEL : +60(3)7958-8355	FAX : +60(3)7958-8377
Philippines / Manila	TEL : +63(2)807-6872	FAX : +63(2)809-1422
Thailand / Bangkok	TEL : +66(2)254-4890	FAX : +66(2)256-6334

Tokyo	2-1-1, Yaesu, Chuo-ku, Tokyo 104-0082 TEL : +81(3)5203-0321 FAX : +81(3)5203-0300
Yokohama	2-4-8, Shin Yokohama, Kohoku-ku, Yokohama, Kanagawa 222-8575 TEL : +81(45)476-2131 FAX : +81(45)476-2128
Nagoya	Dainagayo Building 9F 3-28-12, Meieki, Nakamura-ku, Nagoya,Aichi 450-0002 TEL : +81(52)581-8521 FAX : +81(52)561-2173
Kyoto	579-32 Higashi Shiokouji-cho, Karasuma Nishi-iru, Shiokoujidori, Shimogyo-ku Kyoto 600-8216 TEL : +81(75)311-2121 FAX : +81(75)314-6559
Contact addr	ess for overseas customers in Japan)
Yokohama	TEL : +81(45)476-9270 FAX : +81(045)476-9271

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